



地址显光活治海岛于历人通兴汉四

ADD: TDG Technology Park, Hanning Thousand China

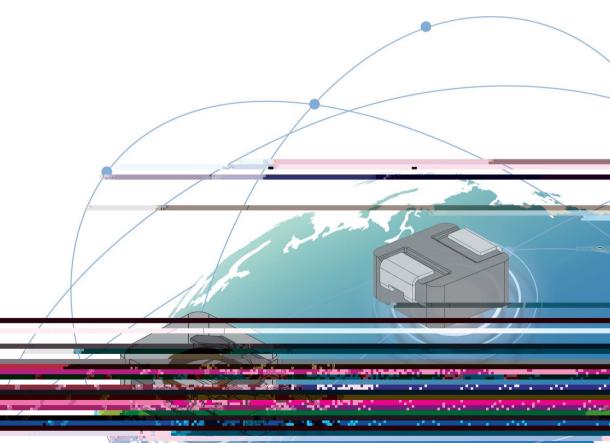
袁生生_Mr, XIIAh.; .+×h-」中央

2023 一体成型思想。



线上商城

微信公众是





TMAX SERIES | TMAX

Company Superiority

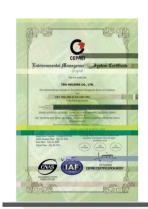
1. Rich Experience of More Than 30 Years in R&D and Production of Magnetic Materials

2. Complete Quality System

5. Professional Technical Team With More Than 10 Years of Experience



















Molding Choke



Die-Casting by Low Loss metal softmagnetic powder

Follow

Good EMC performance and low noise

Voltage Regulator Module

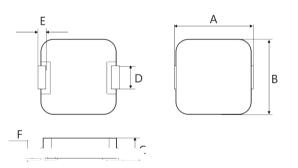
DC/DC Converters

Thin Type on-Board Power Supply Module for Exchanger

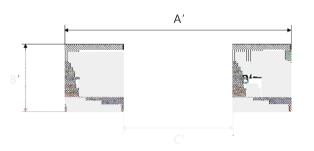
Laptops and PCs

SSD Modules

Dimensions



Recommend Land Pattern Dimensions





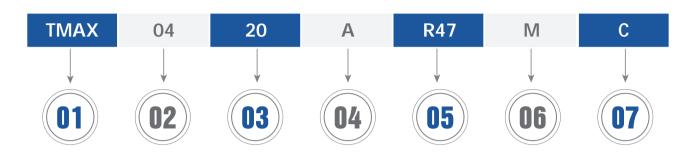
Power Choke

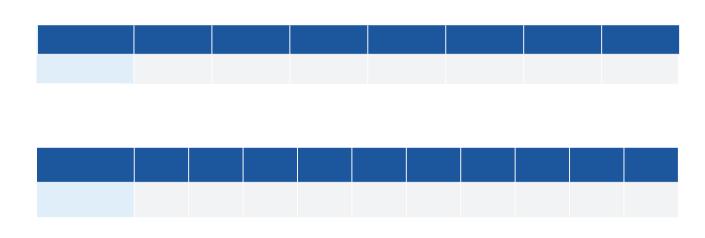






PART NUMBERING







P SPECIFICATION NOTE

All test data is referenced to 25 ambient.

Test Condition:100kHz, 1.0Vrms

Idc: DC current (A) that will cause an approximate T of 40

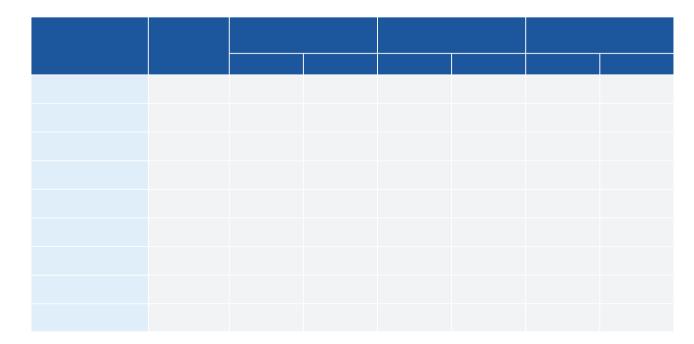
Isat: DC current (A) that will cause Lo to drop approximately 30%

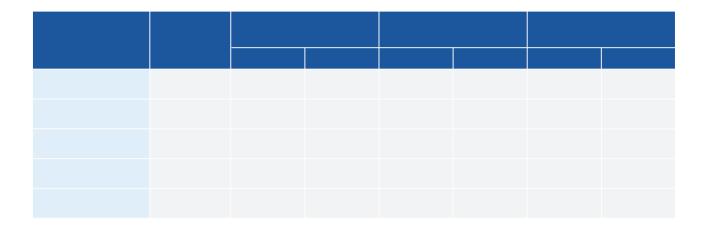
The par temperature (ambient + temp rise) should not exceed 125 under worse case operating conditions. Circuit design , component placement, PWB trace size and thickness, air low and other cooling provision all af ect the par temperature. Par temperature should be verified in the end application.

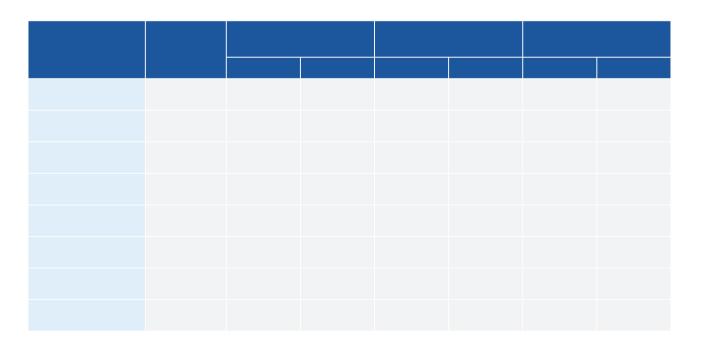
on which value is lower.

SERIES PRODUCT SPECIFICATION

4*4 SERIES



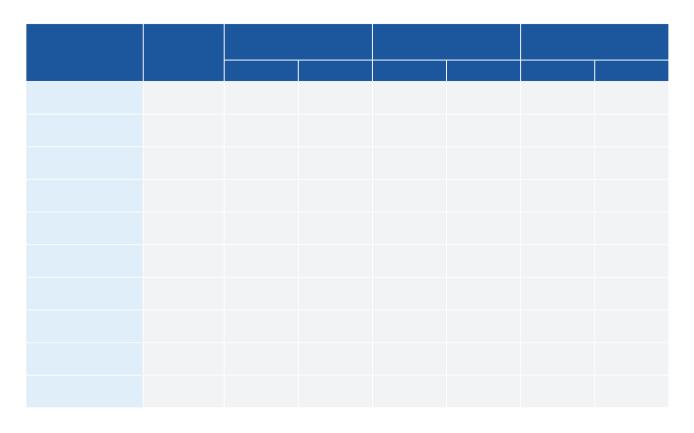


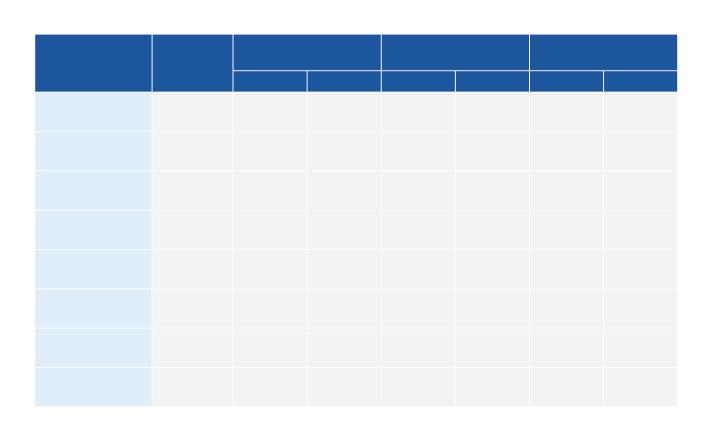


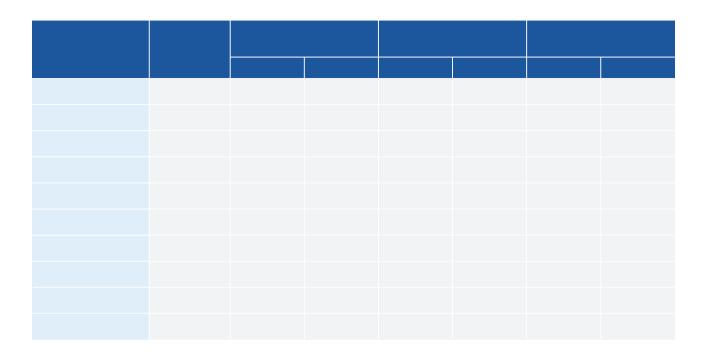




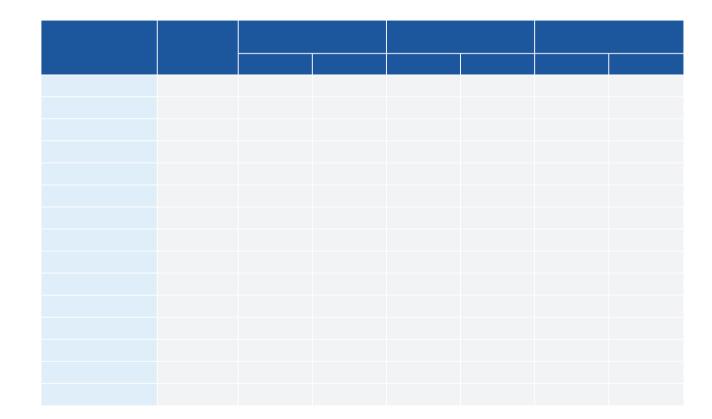
5*5 SERIES



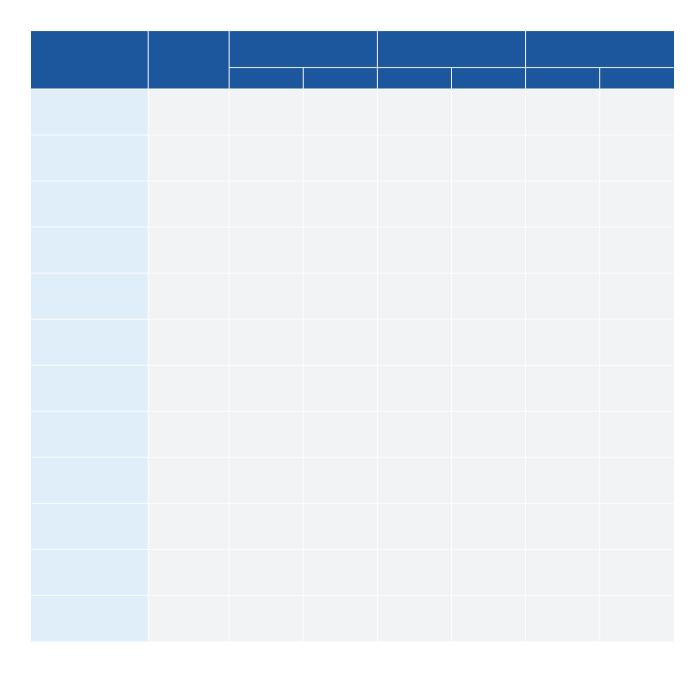




6*6 SERIES







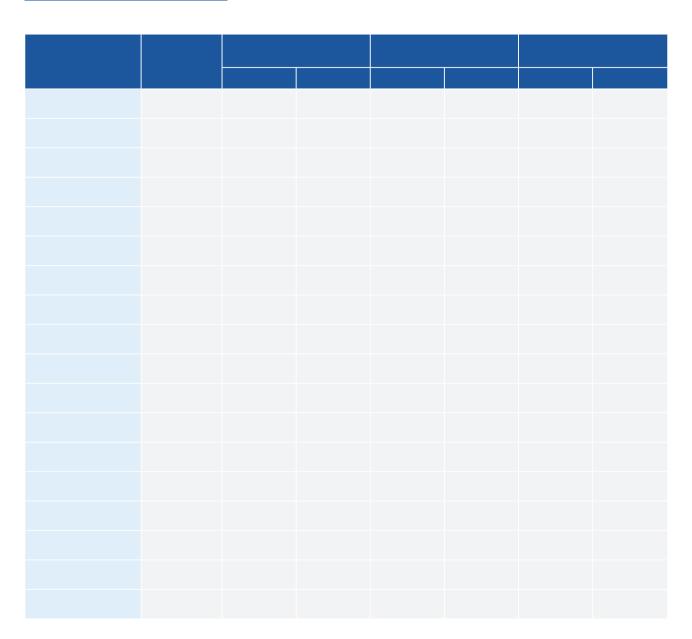
8*8 SERIES

Power Choke



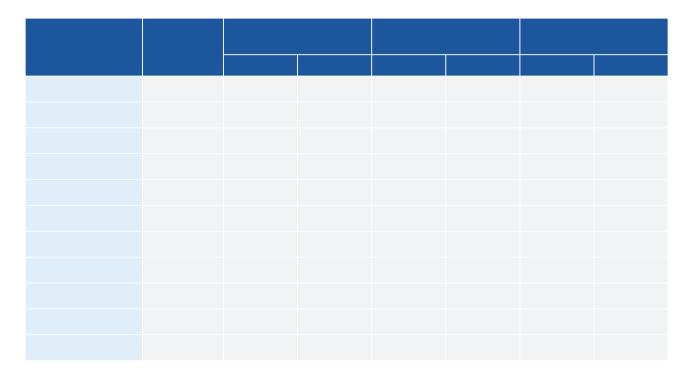


10*10 SERIES





13*13 SERIES

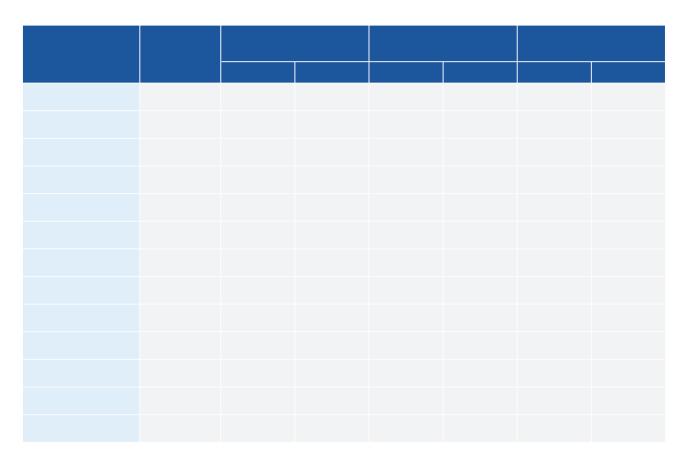


Power Choke





17*17 SERIES







SPECIFICATION NOTE

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Idc: DC current (A) that will cause an approximate T of 40

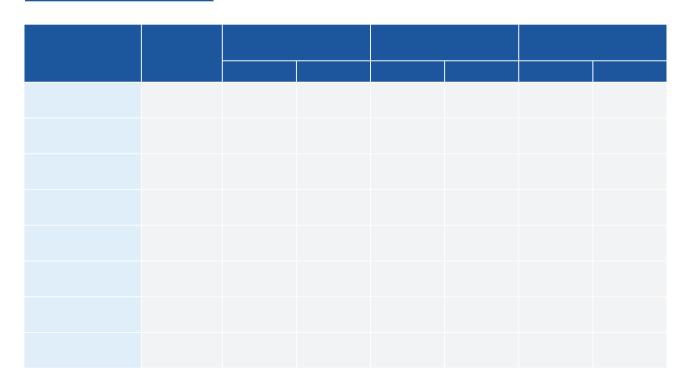
Isat: DC current (A) that will cause Lo to drop approximately 30%

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SERIES PRODUCT SPECIFICATION

4*4 SERIES

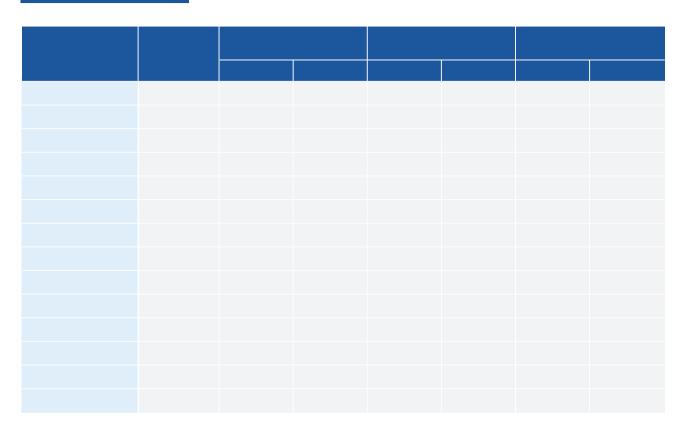




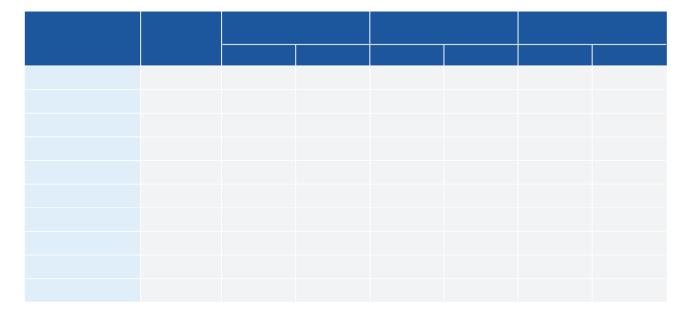




6*6 SERIES



8*8 SERIES

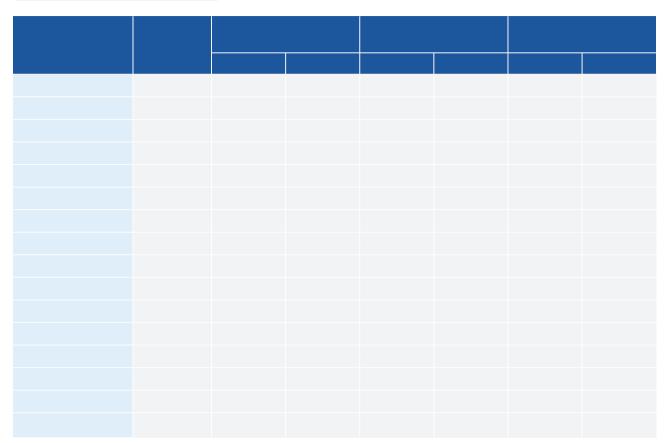








10*10 SERIES



13*13 SERIES

